



# SOT552-1

plastic, thin shrink small outline package; 10 leads; 0.5 mm pitch; 3 mm x 3 mm x 1.1 mm body

9 July 2021

Package information

## 1 Package summary

<b>Terminal position code</b>	D (double)
<b>Package type descriptive code</b>	TSSOP10
<b>Package style descriptive code</b>	TSSOP (thin shrink small outline package)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	08-07-2021
<b>Manufacturer package code</b>	SOT552

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.9	3	3.1	mm
package width	2.9	3	3.1	mm
seated height	-	-	1.1	mm
package height	0.8	0.9	0.95	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	10	-	



plastic, thin shrink small outline package; 10 leads; 0.5 mm pitch; 3 mm x 3 mm x 1.1 mm body

2 Package outline

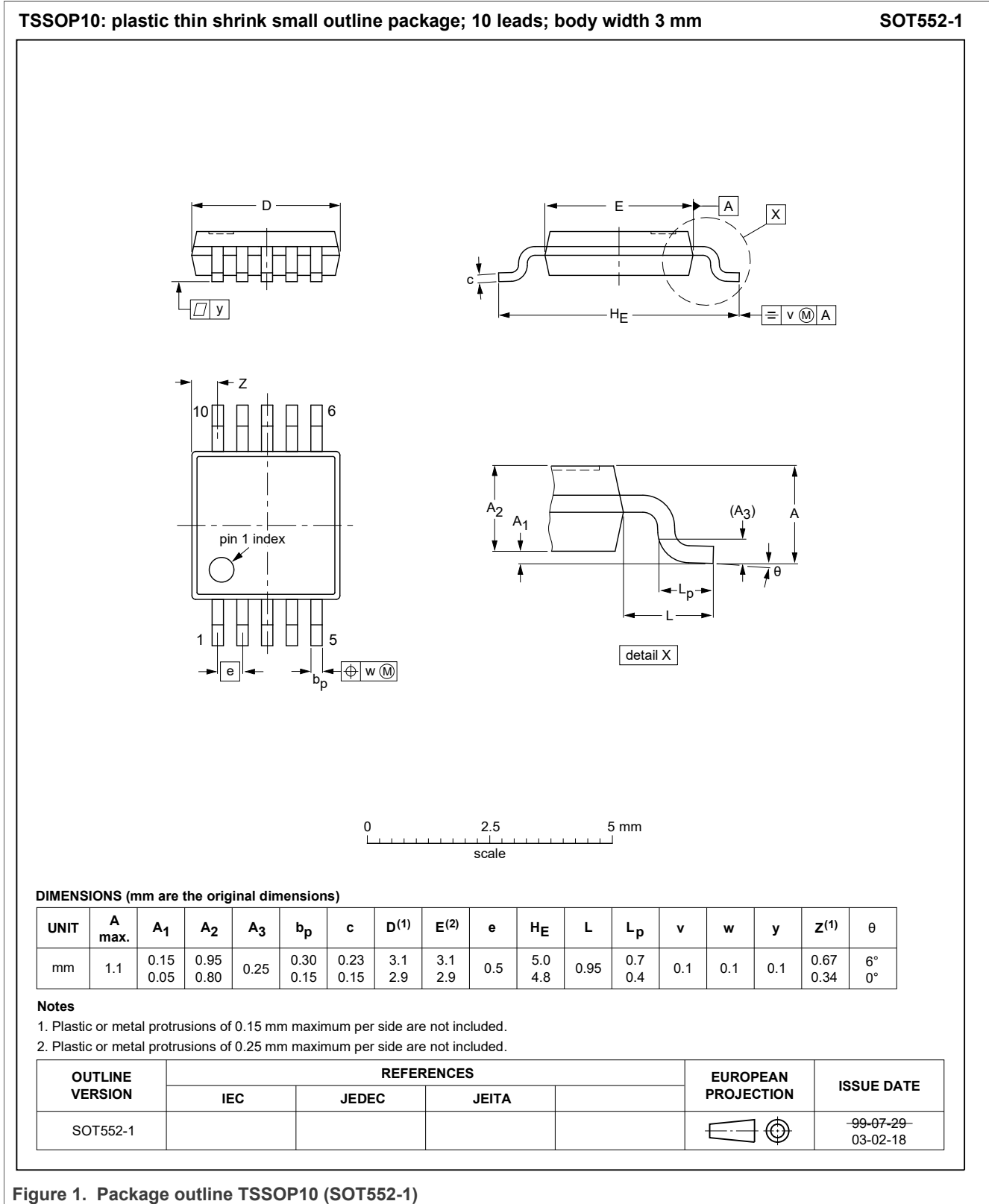
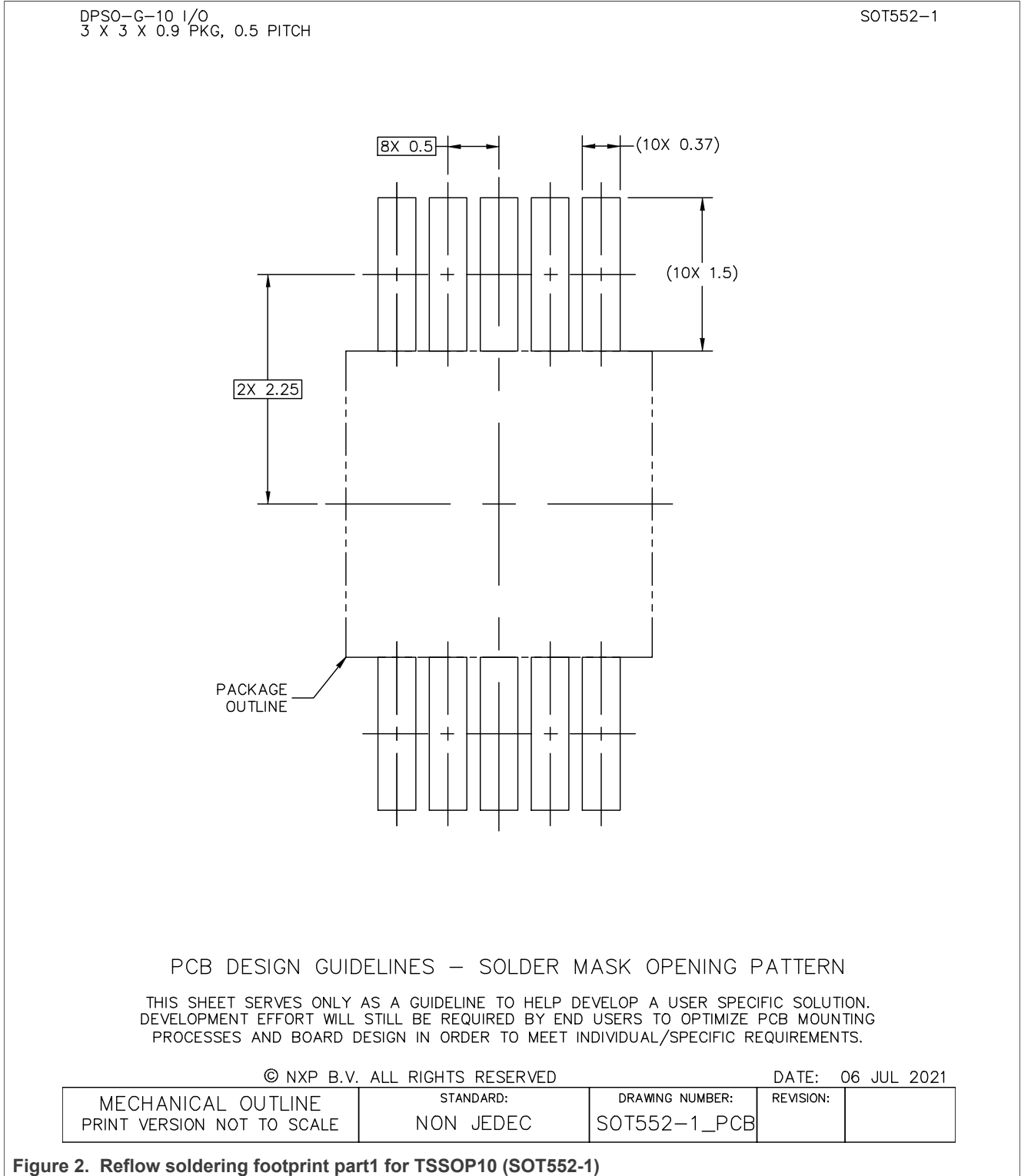


Figure 1. Package outline TSSOP10 (SOT552-1)

plastic, thin shrink small outline package; 10 leads; 0.5 mm pitch; 3 mm x 3 mm x 1.1 mm body

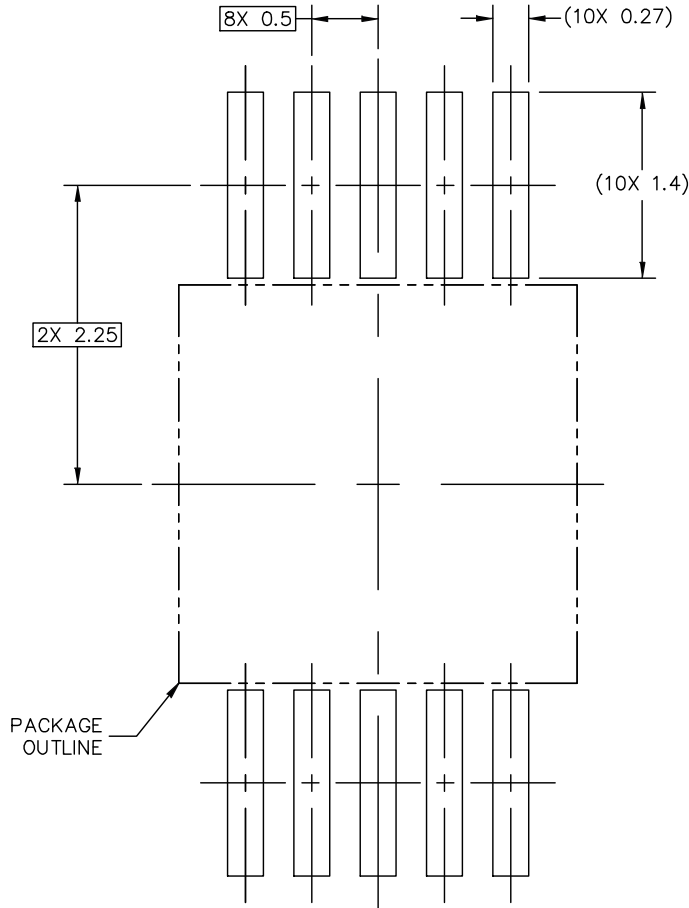
3 Soldering



plastic, thin shrink small outline package; 10 leads; 0.5 mm pitch; 3 mm x 3 mm x 1.1 mm body

DPSO-G-10 I/O  
3 X 3 X 0.9 PKG, 0.5 PITCH

SOT552-1



PCB DESIGN GUIDELINES – I/O PADS AND SOLDERABLE AREA

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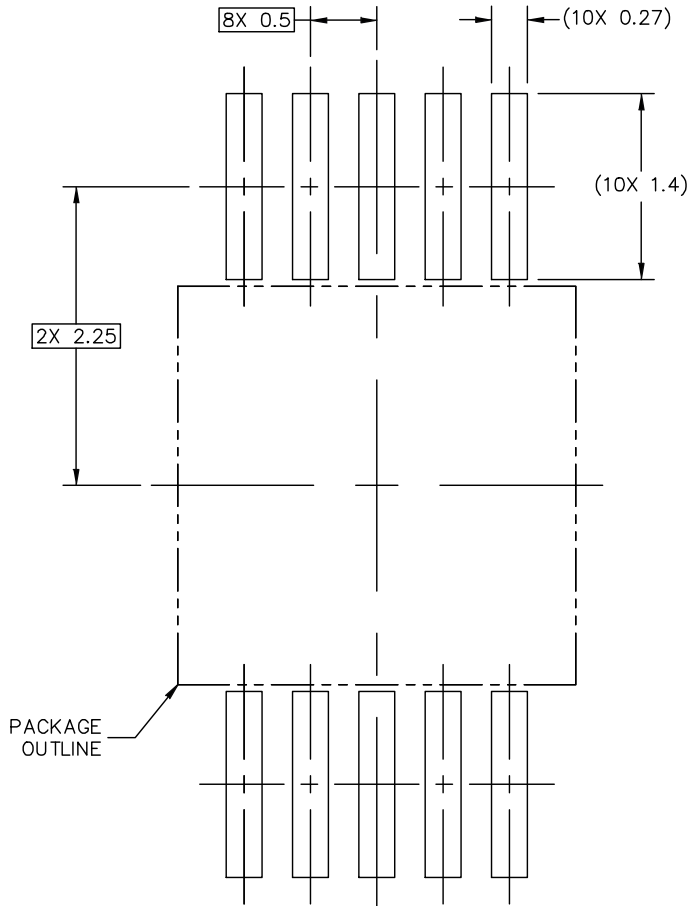
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT552-1_PCB	REVISION:
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Figure 3. Reflow soldering footprint part2 for TSSOP10 (SOT552-1)

plastic, thin shrink small outline package; 10 leads; 0.5 mm pitch; 3 mm x 3 mm x 1.1 mm body

DPSO-G-10 I/O  
3 X 3 X 0.9 PKG, 0.5 PITCH

SOT552-1



RECOMMENDED STENCIL THICKNESS 0.125 OR 0.15

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Figure 4. Reflow soldering footprint part3 for TSSOP10 (SOT552-1)

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plastic, thin shrink small outline package; 10 leads; 0.5 mm pitch; 3 mm x 3 mm x 1.1 mm body

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## 4 Legal information

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